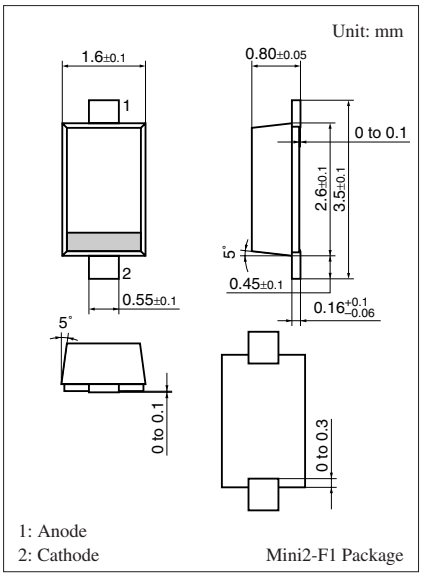
MA2YD21

Silicon epitaxial planar type

For high frequency rectification



Marking Symbol: 2X

■ Features

- Forward current (Average) $I_{F(AV)}$ = 1 A rectification is possible
- Low forward voltage: V_F < 0.4 V

■ Absolute Maximum Ratings T_a = 25°C

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	15	V
Repetitive peak reverse voltage	V_{RRM}	15	V
Forward current (Average) *1	$I_{F(AV)}$	1.0	A
Non-repetitive peak forward surge current *2	I_{FSM}	3	A
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	−55 to +125	°C

Note) ∗1: Mounted on an alumina PC board

∗2: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

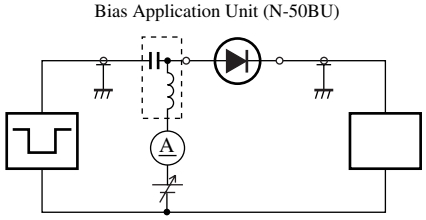
■ Electrical Characteristics T_a = 25°C ± 3°C

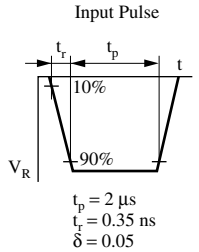
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	I_F = 1 A			0.4	V
Reverse current	I_R	V_R = 6 V			1.5	mA
Terminal capacitance	C_t	V_R = 0 V, f = 1 MHz		180		pF
Reverse recovery time *	t_{rr}	I_F = I_R = 100 mA I_{rr} = 10 mA, R_L = 100 Ω		12		ns

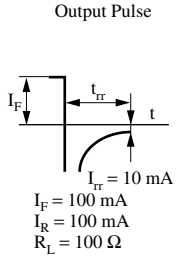
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

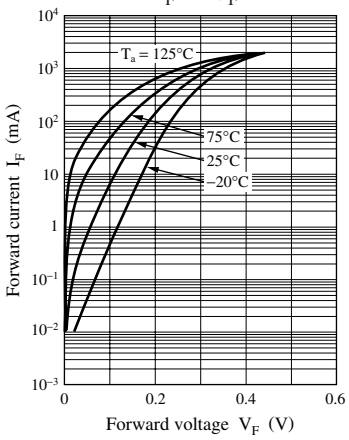
3. ∗: t_{rr} measurement circuit



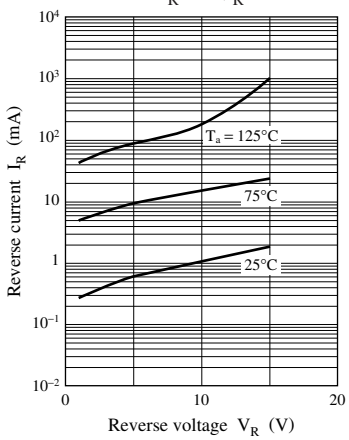




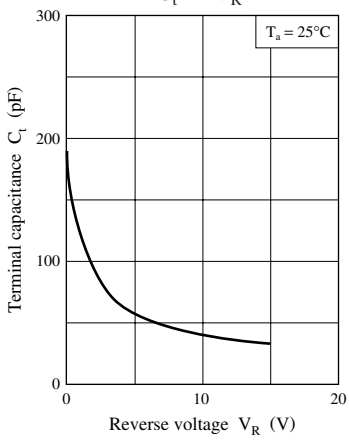
I_F — V_F



I_R — V_R



C_t — V_R



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